

	Type	L #	Hits	Search Text	DBs
1	BRS	L1	458	Schottky near2 interface	USPAT; US-PGPUB; EPO; JPO; DERWENT
2	BRS	L2	436	1 and (film layer pad sheet)	USPAT; US-PGPUB; EPO; JPO; DERWENT
3	BRS	L3	10	2 and (shunt\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT
4	BRS	L4	2	3 and (strain stress)	USPAT; US-PGPUB; EPO; JPO; DERWENT
5	BRS	L5	280	1 and (semiconduct\$5) near2 (film layer pad sheet)	USPAT; US-PGPUB; EPO; JPO; DERWENT
6	BRS	L6	5	5 and (shunt)	USPAT; US-PGPUB; EPO; JPO; DERWENT
7	BRS	L7	1	6 and (strain stress)	USPAT; US-PGPUB; EPO; JPO; DERWENT
8	BRS	L8	2	6 and (pressure load force strain stress)	USPAT; US-PGPUB; EPO; JPO; DERWENT
9	BRS	L9	2	8 and (control\$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT
10	BRS	L10	2	9 and (voltage current)	USPAT; US-PGPUB; EPO; JPO; DERWENT
11	BRS	L11	49992	(measur\$5 detect\$5 sens\$5 transducer) near2 (strain stress)	USPAT; US-PGPUB; EPO; JPO; DERWENT
12	BRS	L12	6	11 and Schottky near2 interface	USPAT; US-PGPUB; EPO; JPO; DERWENT
13	BRS	L13	1	12 and (shunt)	USPAT; US-PGPUB; EPO; JPO; DERWENT
14	BRS	L14	1	12 and (shunt\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT
15	BRS	L15	162	11 and Schottky	USPAT; US-PGPUB; EPO; JPO; DERWENT
16	BRS	L16	8	15 and (shunt)	USPAT; US-PGPUB; EPO; JPO; DERWENT
17	BRS	L17	239929	(semiconduct\$5) near2 (film layer pad sheet)	USPAT; US-PGPUB; EPO; JPO; DERWENT
18	BRS	L18	61	17 near3 (shunt)	USPAT; US-PGPUB; EPO; JPO; DERWENT
19	BRS	L19	7	18 and Schottky	USPAT; US-PGPUB; EPO; JPO; DERWENT
20	BRS	L20	0	17 near3 (metla\$5) near2 (shunt)	USPAT; US-PGPUB; EPO; JPO; DERWENT

	Time Stamp	Comments	Error Definition	Errors
1	2004/10/25 11:26			0
2	2004/10/25 11:16			0
3	2004/10/25 11:16			0
4	2004/10/25 11:17			0
5	2004/10/25 11:38			0
6	2004/10/25 11:27			0
7	2004/10/25 11:18			0
8	2004/10/25 11:18			0
9	2004/10/25 11:18			0
10	2004/10/25 11:18			0
11	2004/10/25 11:26			0
12	2004/10/25 11:27			0
13	2004/10/25 11:39			0
14	2004/10/25 11:27			0
15	2004/10/25 11:39			0
16	2004/10/25 11:27			0
17	2004/10/25 11:42			0
18	2004/10/25 11:41			0
19	2004/10/25 11:41			0
20	2004/10/25 11:41			0

	Type	L #	Hits	Search Text	DBs
21	BRS	L21	0	17 near3 (meta\$15) near2 (shunt)	USPAT; US-PGPUB; EPO; JPO; DERWENT
22	BRS	L22	9	17 near3 (metal\$5) near2 (shunt)	USPAT; US-PGPUB; EPO; JPO; DERWENT
23	BRS	L23	2	22 and Schottky	USPAT; US-PGPUB; EPO; JPO; DERWENT
24	BRS	L24	468	(metal\$5) near2 (shunt)	USPAT; US-PGPUB; EPO; JPO; DERWENT
25	BRS	L25	63	24 and (semiconduct\$5) near2 (film layer pad sheet)	USPAT; US-PGPUB; EPO; JPO; DERWENT
26	BRS	L26	4	25 and Schottky	USPAT; US-PGPUB; EPO; JPO; DERWENT

	Time Stamp	Comments	Error Definition	Errors
21	2004/10/25 11:41			0
22	2004/10/25 11:42			0
23	2004/10/25 11:42			0
24	2004/10/25 11:42			0
25	2004/10/25 11:42			0
26	2004/10/25 11:42			0

	Type	L #	Hits	Search Text	DBs
1	BRS	L1	458	Schottky near2 interface	USPAT; US-PGPUB; EPO; JPO; DERWENT
2	BRS	L2	436	1 and (film layer pad sheet)	USPAT; US-PGPUB; EPO; JPO; DERWENT
3	BRS	L3	10	2 and (shunt\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT
4	BRS	L4	2	3 and (strain stress)	USPAT; US-PGPUB; EPO; JPO; DERWENT
5	BRS	L5	280	1 and (semiconduct\$5) near2 (film layer pad sheet)	USPAT; US-PGPUB; EPO; JPO; DERWENT
6	BRS	L6	5	5 and (shunt)	USPAT; US-PGPUB; EPO; JPO; DERWENT
7	BRS	L7	1	6 and (strain stress)	USPAT; US-PGPUB; EPO; JPO; DERWENT
8	BRS	L8	2	6 and (pressure load force strain stress)	USPAT; US-PGPUB; EPO; JPO; DERWENT
9	BRS	L9	2	8 and (control\$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT
10	BRS	L10	2	9 and (voltage current)	USPAT; US-PGPUB; EPO; JPO; DERWENT

	Time Stamp	Comments	Error Definition	Errors
1	2004/10/25 11:15			0
2	2004/10/25 11:16			0
3	2004/10/25 11:16			0
4	2004/10/25 11:17			0
5	2004/10/25 11:16			0
6	2004/10/25 11:16			0
7	2004/10/25 11:18			0
8	2004/10/25 11:18			0
9	2004/10/25 11:18			0
10	2004/10/25 11:18			0